Elektronische Bauelemente

SSG8503-C

N-Ch: 10.4A, 30V, $R_{DS(ON)}$ 12mΩ
P-Ch: -9.6A, -30V, $R_{DS(ON)}$ 14mΩ
N & P-Ch Enhancement Mode Power MOSFET

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

DESCRIPTION

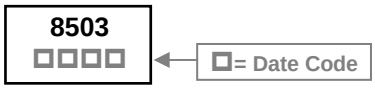
The SSG8503-C is the highest performance trench N-ch and P-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The SSG8503-C meet the RoHS and Green Product requirement with full function reliability approved.

FEATURES

- Advanced High Cell Density Trench Technology
- Super Low Gate Charge
- Green Device Available

MARKING



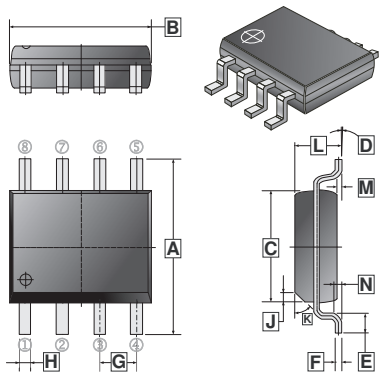
PACKAGE INFORMATION

Package	MPQ	Leader Size
SOP-8	2.5K	13 inch

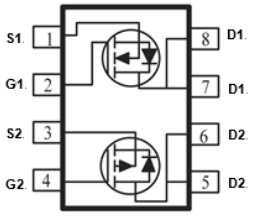
ORDER INFORMATION

Part Number	Type
SSG8503-C	Lead (Pb)-free and Halogen-free

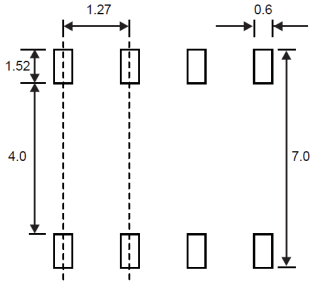
SOP-8



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	5.79	6.20	H	0.33	0.51
B	4.70	5.11	J	0.375 REF.	
C	3.80	4.00	K	45°REF.	
D	0°	8°	L	1.3	1.752
E	0.40	1.27	M	0	0.25
F	0.10	0.25	N	0.25 REF.	
G	1.27 TYP.				



Mounting Pad Layout



*Dimensions in millimeters

ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Ratings		Unit
			N-Ch	P-Ch	
Drain-Source Voltage		V_{DS}	30	-30	V
Gate-Source Voltage		V_{GS}	±20	±20	V
Continuous Drain Current [1] @V_{GS}=10V	T_A=25℃	I_D	10.4	-9.6	A
	T_A=70℃		8.3	-7.8	
Pulsed Drain Current [3]		I_{DM}	36	-36	A
Total Power Dissipation [1]	T_A=25℃	P_D	2		W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55~150		℃
Thermal Data					
Thermal Resistance Junction-Ambient [1]		$R_{\theta JA}$	t≦10s, 62		°C/W
			Steady State, 83		
Thermal Resistance Junction-Ambient [2]			135		
Thermal Resistance Junction-Case [1]		$R_{\theta JC}$	50		

N-CH ELECTRICAL CHARACTERISTICS (T_J=25℃ unless otherwise specified)

Parameter		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage		BV_{DSS}	30	-	-	V	V_{GS}=0, I_D=250μA
Gate Threshold Voltage		$V_{GS(th)}$	1	-	2.5	V	V_{DS}=V_{GS}, I_D=250μA
Forward Transconductance		g_{fs}	-	34	-	S	V_{DS}=5V, I_D=30A
Gate-Source Leakage Current		I_{GSS}	-	-	±100	nA	V_{GS}= ±20V
Drain-Source Leakage Current	T_J=25℃	I_{DSS}	-	-	1	μA	V_{DS}=24V, V_{GS}=0
	T_J=55℃		-	-	5		
Static Drain-Source On-Resistance [4]		$R_{DS(ON)}$	-	9	12	mΩ	V_{GS}=10V, I_D=9A
			-	14	18		V_{GS}=4.5V, I_D=5A
Total Gate Charge		Q_g	-	9.8	-	nC	I_D=9A V_{DS}=15V V_{GS}=4.5V
Gate-Source Charge		Q_{gs}	-	4.2	-		
Gate-Drain (“Miller”) Change		Q_{gd}	-	3.6	-		
Turn-on Delay Time		$T_{d(on)}$	-	4	-	nS	V_{DD}=15V V_{GS}=10V I_D=9A R_G=3.3Ω
Rise Time		T_r	-	8	-		
Turn-off Delay Time		$T_{d(off)}$	-	31	-		
Fall Time		T_f	-	4	-		
Input Capacitance		C_{iss}	-	940	-	pF	V_{GS}=0 V_{DS}=15V f=1MHz
Output Capacitance		C_{oss}	-	131	-		
Reverse Transfer Capacitance		C_{rss}	-	109	-		
Source-Drain Diode							
Forward on Voltage [4]		V_{SD}	-	-	1.2	V	I_S=1A, V_{GS}=0
Continuous Source Current [1]		I_S	-	-	10.4	A	
Pulsed Source Current [3]		I_{SM}	-	-	36	A	
Reverse Recovery Time		T_{rr}	-	8.5	-	nS	I_F=30A, dI/dt=100A/μs, T_J=25℃
Reverse Recovery Charge		Q_{rr}	-	2.2	-	nC	

Notes:
1. Surface mounted on a 1 inch^2 FR-4 board with 2oz copper.
2. When mounted on Min. copper pad.
3. Pulse width limited by maximum junction temperature, Pulse Width≤300μs, Duty Cycle≤2%.
4. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%.

P-CH ELECTRICAL CHARACTERISTICS (T_J=25°C unless otherwise specified)

Parameter		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage		BV_{DSS}	-30	-	-	V	V_{GS}=0, I_D= -250μA
Gate Threshold Voltage		$V_{GS(th)}$	-1	-	-2.5	V	V_{DS}=V_{GS}, I_D= -250μA
Forward Transconductance		g_{fs}	-	30	-	S	V_{DS}= -5V, I_D= -30A
Gate-Source Leakage Current		I_{GSS}	-	-	±100	nA	V_{GS}= ±20V
Drain-Source Leakage Current	T_J=25℃	I_{DSS}	-	-	-1	μA	V_{DS}= -24V, V_{GS}=0
	T_J=55℃		-	-	-5		
Static Drain-Source On-Resistance [4]		$R_{DS(ON)}$	-	10	14	mΩ	V_{GS}= -10V, I_D= -8.3A
			-	15	20		V_{GS}= -4.5V, I_D= -4A
Total Gate Charge		Q_g	-	22	-	nC	I_D= -8.3A V_{DS}= -15V V_{GS}= -4.5V
Gate-Source Charge		Q_{gs}	-	8.7	-		
Gate-Drain (“Miller”) Change		Q_{gd}	-	7.2	-		
Turn-on Delay Time		$T_{d(on)}$	-	8	-	nS	V_{DD}= -15V V_{GS}= -10V I_D= -8.3A R_G=3.3Ω
Rise Time		T_r	-	73.7	-		
Turn-off Delay Time		$T_{d(off)}$	-	61.8	-		
Fall Time		T_f	-	24.4	-		
Input Capacitance		C_{iss}	-	2215	-	pF	V_{GS}=0 V_{DS}= -15V f=1MHz
Output Capacitance		C_{oss}	-	310	-		
Reverse Transfer Capacitance		C_{rss}	-	237	-		
Source-Drain Diode							
Forward On Voltage [4]		V_{SD}	-	-	-1.2	V	I_S= -1A, V_{GS}=0V
Continuous Source Current [1]		I_S	-	-	-9.6	A	
Pulsed Source Current [3]		I_{SM}	-	-	-36	A	
Reverse Recovery Time		T_{rr}	-	19	-	nS	I_F= -15A, dI/dt=100A/μs, T_J=25℃
Reverse Recovery Charge		Q_{rr}	-	9	-	nC	

Notes:
1. Surface mounted on a 1 inch^2 FR-4 board with 2oz copper.
2. When mounted on Min. copper pad.
3. Pulse width limited by maximum junction temperature, Pulse Width≤300μs, Duty Cycle≤2%.
4. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%.

CHARACTERISTIC CURVE (N-Ch)

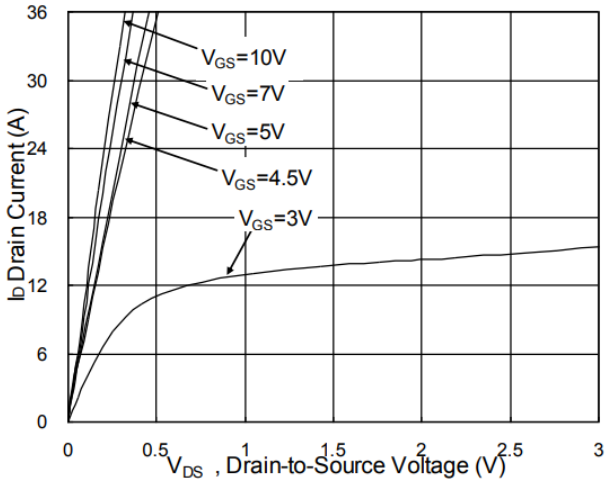


Fig.1 Typical Output Characteristics

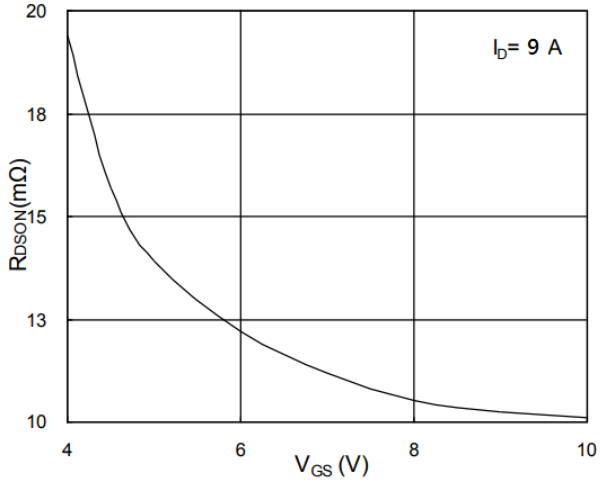


Fig.2 On-Resistance vs. G-S Voltage

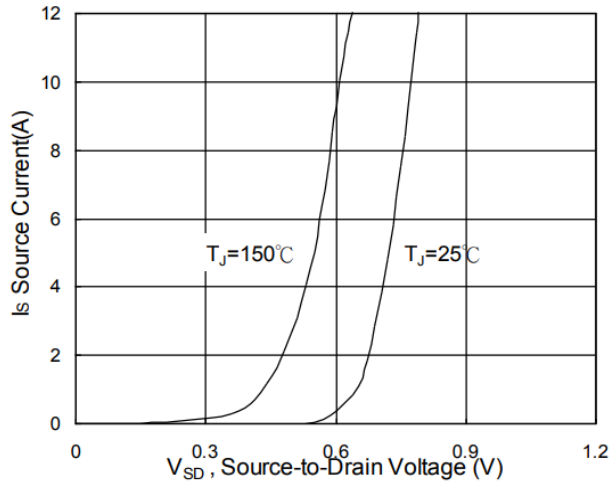


Fig.3 Forward Characteristics of Reverse

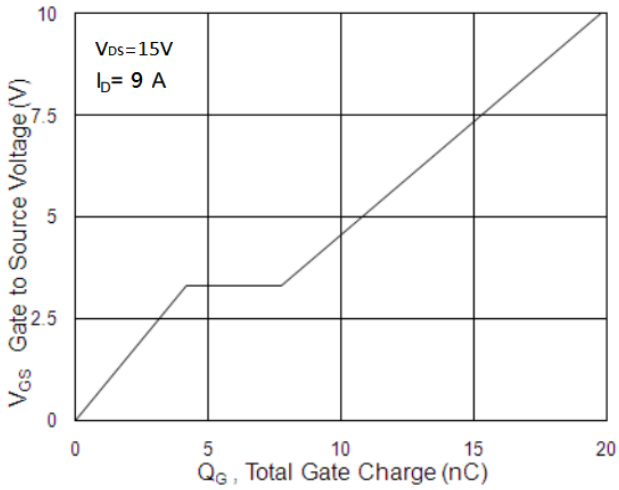


Fig.4 Gate-Charge Characteristics

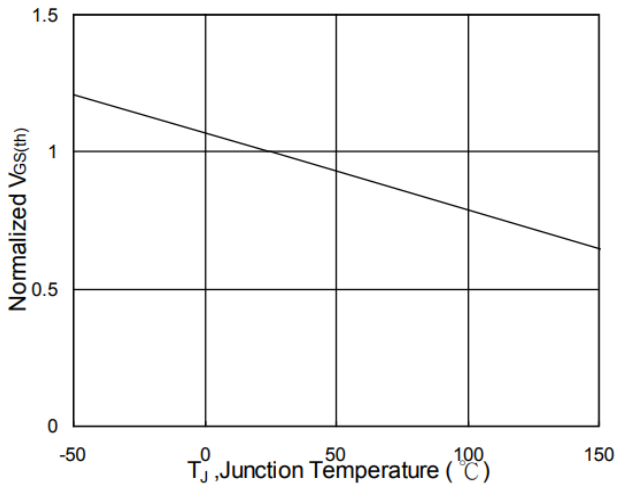


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

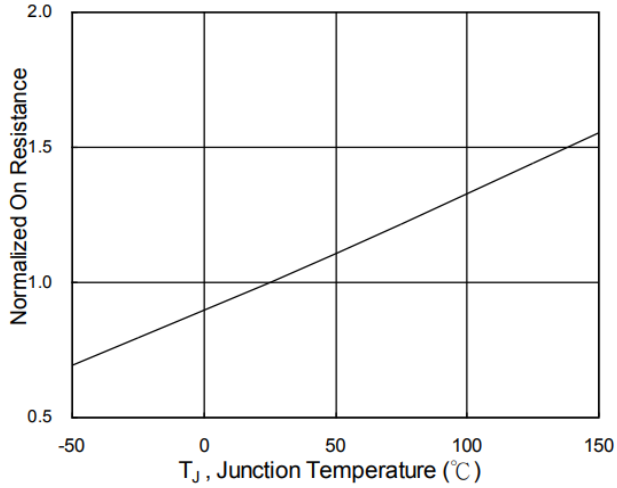


Fig.6 Normalized R_{DSON} vs. T_J

CHARACTERISTIC CURVE (N-Ch)

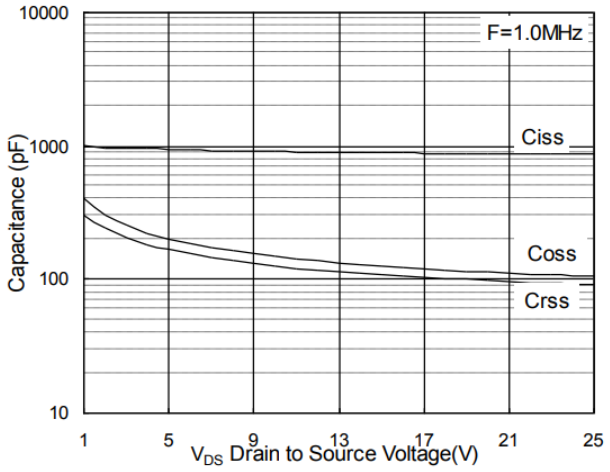


Fig.7 Capacitance

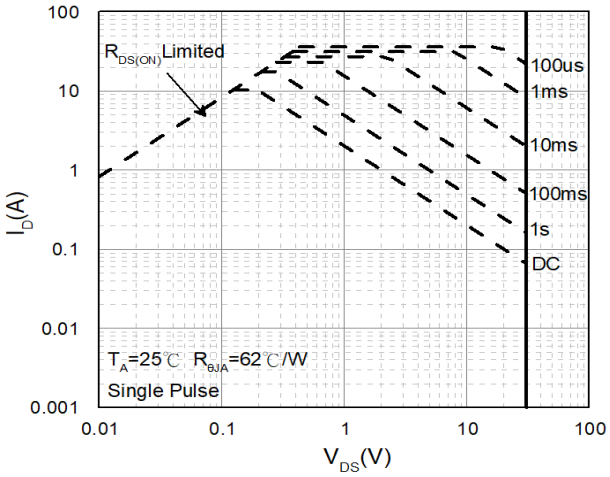


Fig.8 Safe Operating Area

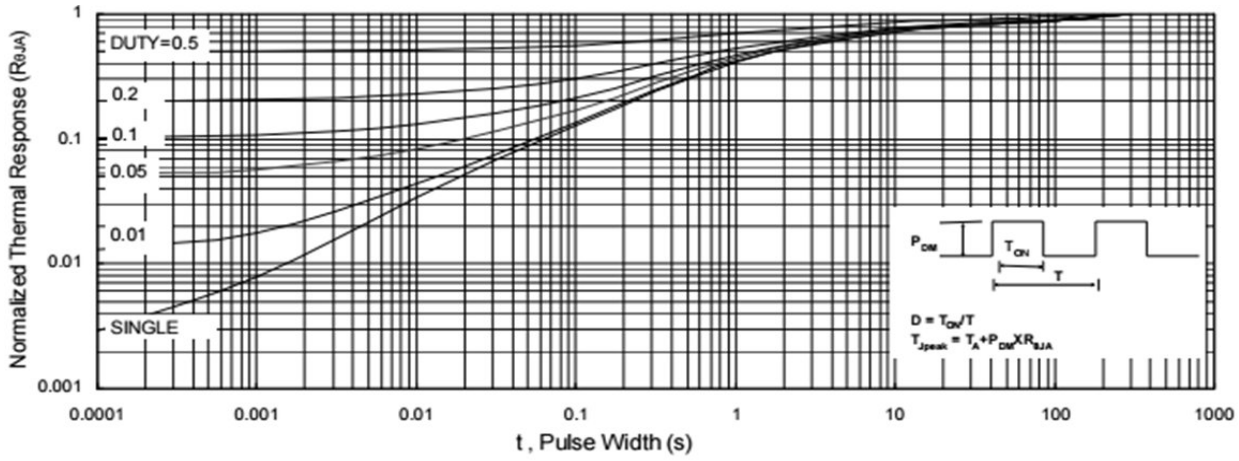


Fig.9 Normalized Maximum Transient Thermal Impedance

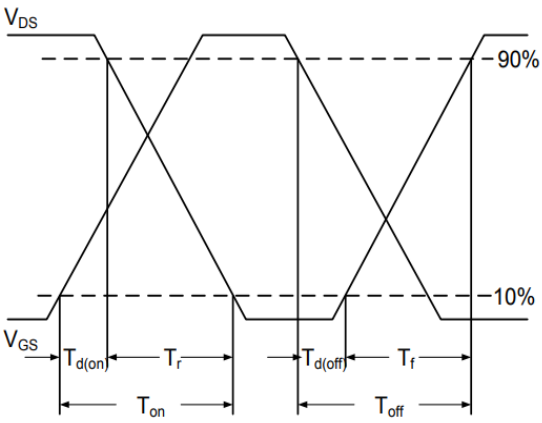


Fig.10 Switching Time Waveform

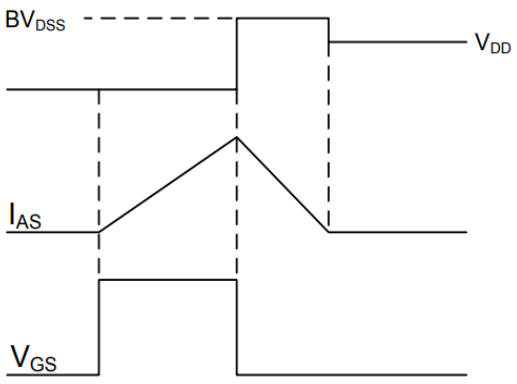


Fig.11 Unclamped Inductive Switching Waveform

CHARACTERISTIC CURVE (P-Ch)

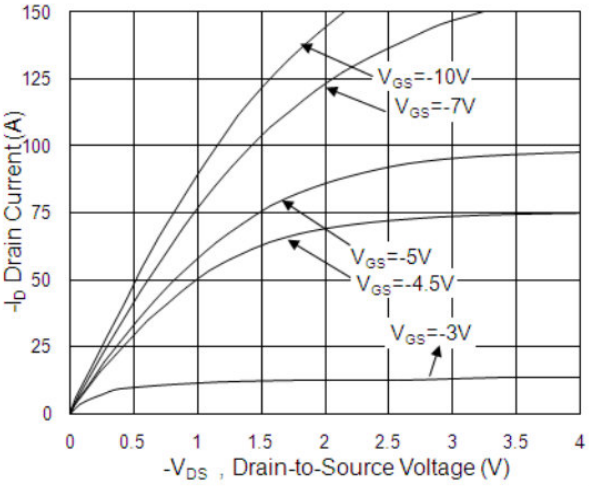


Fig.1 Typical Output Characteristics

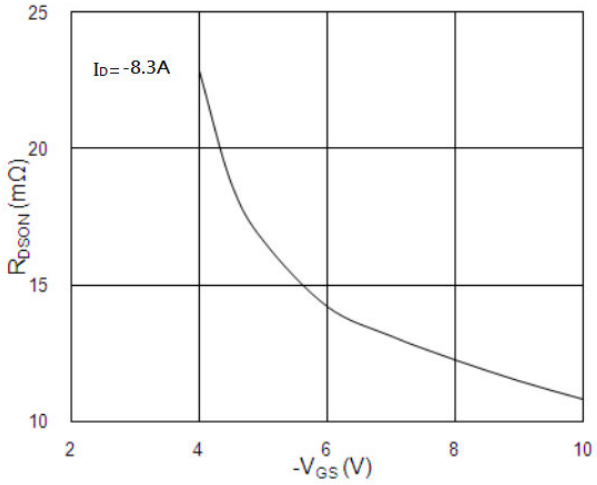


Fig.2 On-Resistance vs. G-S Voltage

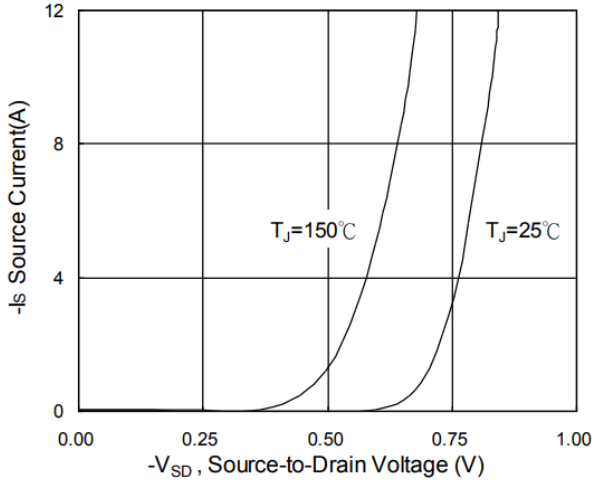


Fig.3 Forward Characteristics of Reverse

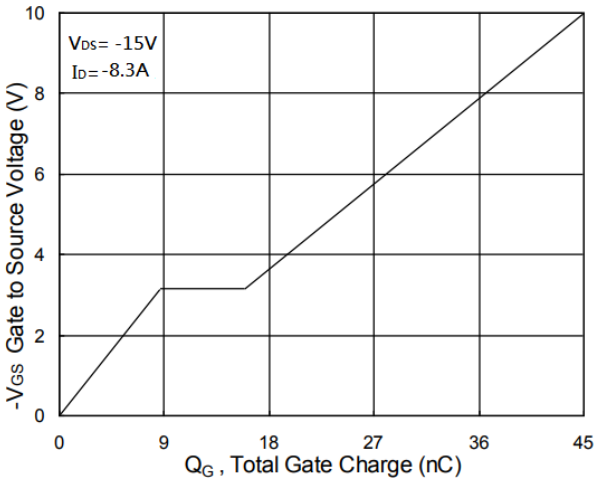


Fig.4 Gate-charge Characteristics

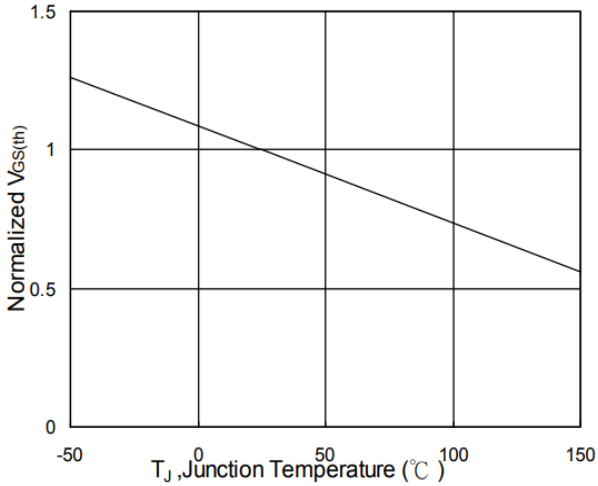


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

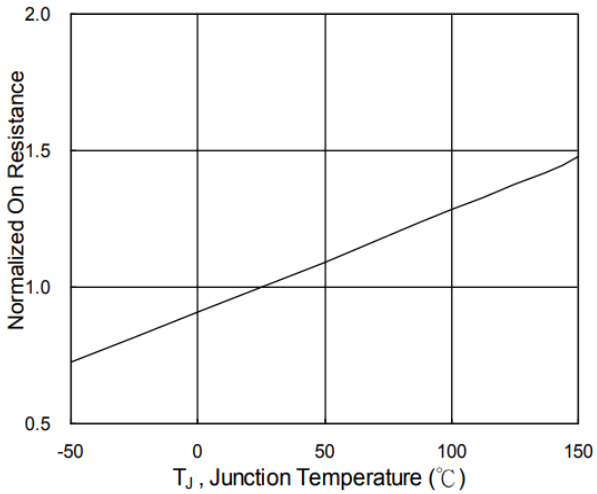


Fig.6 Normalized R_{DSON} vs. T_J

CHARACTERISTIC CURVE (P-Ch)

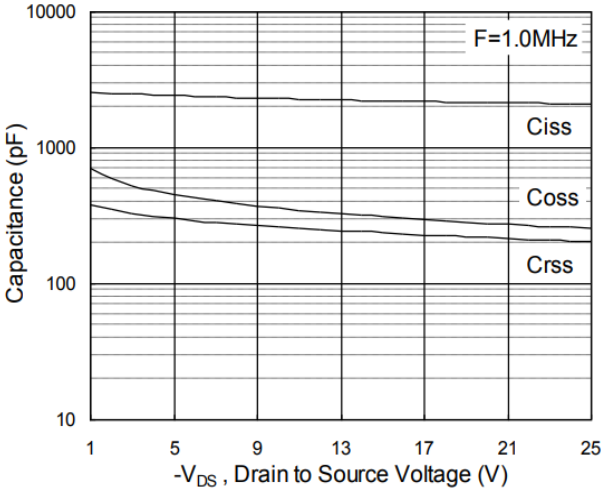
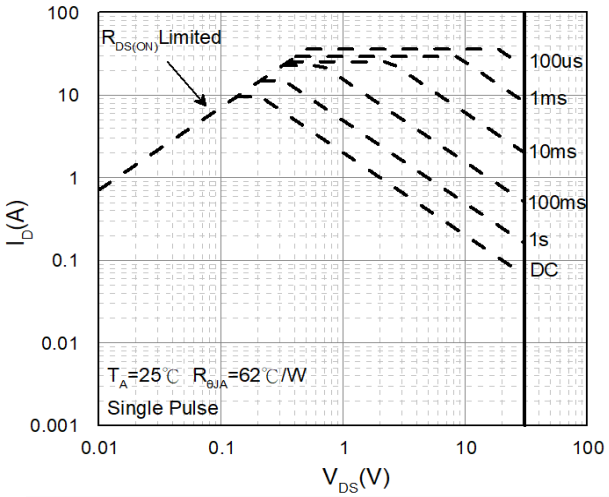


Fig.7 Capacitance



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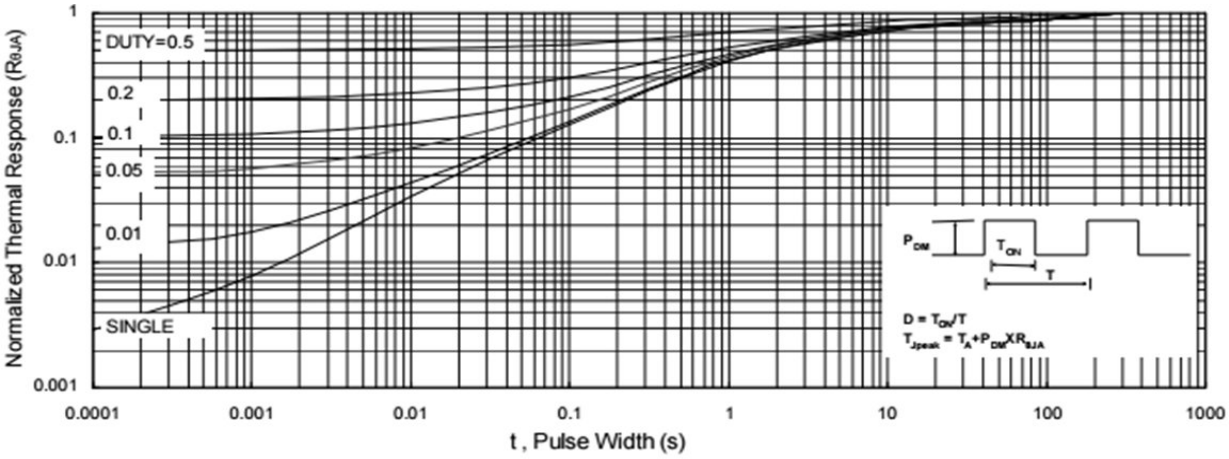

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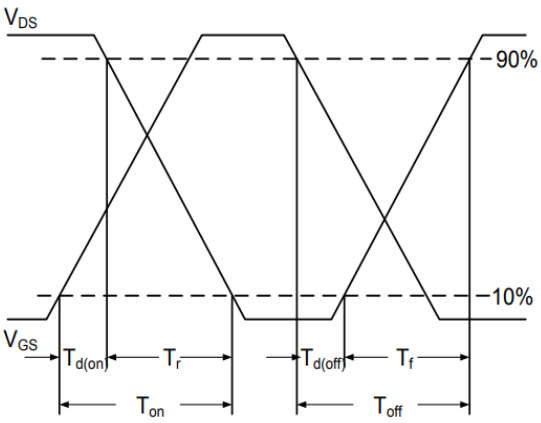

Fig.10 Switching Time Waveform

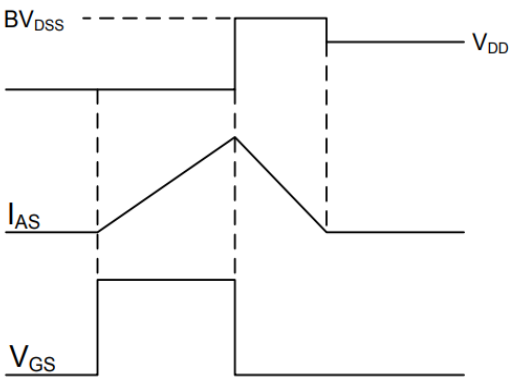

Fig.11 Unclamped Inductive Switching Waveform